SN74AS1008A
QUADRUPLE 2-INPUT POSITIVE-AND BUFFER/DRIVER

- **Driver Version of ′AS08**
- **Offers High Capacitive-Drive Capability**
- **Package Options Include Plastic Small-Outline (D) Packages and Standard Plastic (N) 300-mil DIPs**

D OR N PACKAGE
(TOP VIEW)

1A	1	14	V_{CC}
1B	2	13	4B
1Y	3	12	4A
2A	4	11	4Y
2B	5	10	3B
2Y	6	9	3A
GND	7	8	3Y

description

This device contains four independent 2-input positive-AND buffers/drivers. It performs the Boolean functions $Y = A \bullet B$ or $Y = \overline{A} + \overline{B}$ in positive logic.
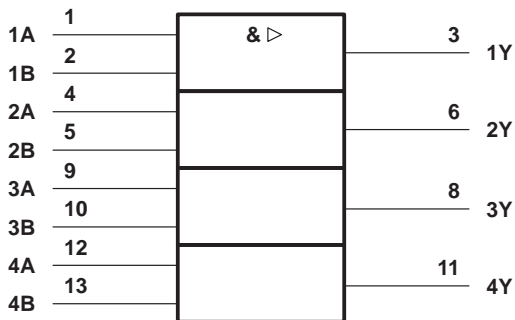
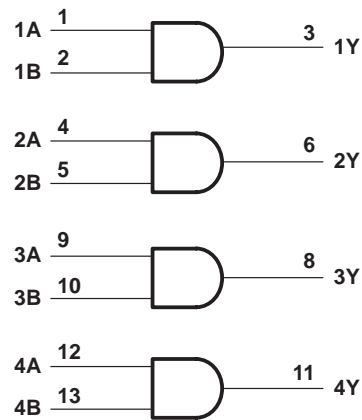The SN74AS1008A is characterized for operation from 0°C to 70°C.
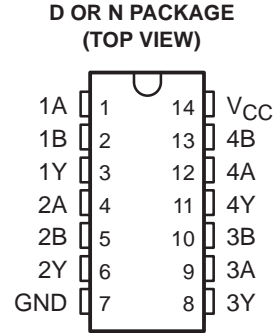
FUNCTION TABLE
(each gate)

INPUTS		OUTPUT
A	**B**	**Y**
H	H	H
L	X	L
X	L	L

logic symbol†

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V_{CC} .... 7 V
Input voltage, V_I .... 7 V
Operating free-air temperature range, T_A .... 0°C to 70°C
Storage temperature range .... −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TEXAS INSTRUMENTS

recommended operating conditions†

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
I_{OH}	High-level output current			−48	mA
I_{OL}	Low-level output current			48	mA
T_A	Operating free-air temperature	0		70	°C

† This high sink- or source-current device is not recommended for use above 40 MHz.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

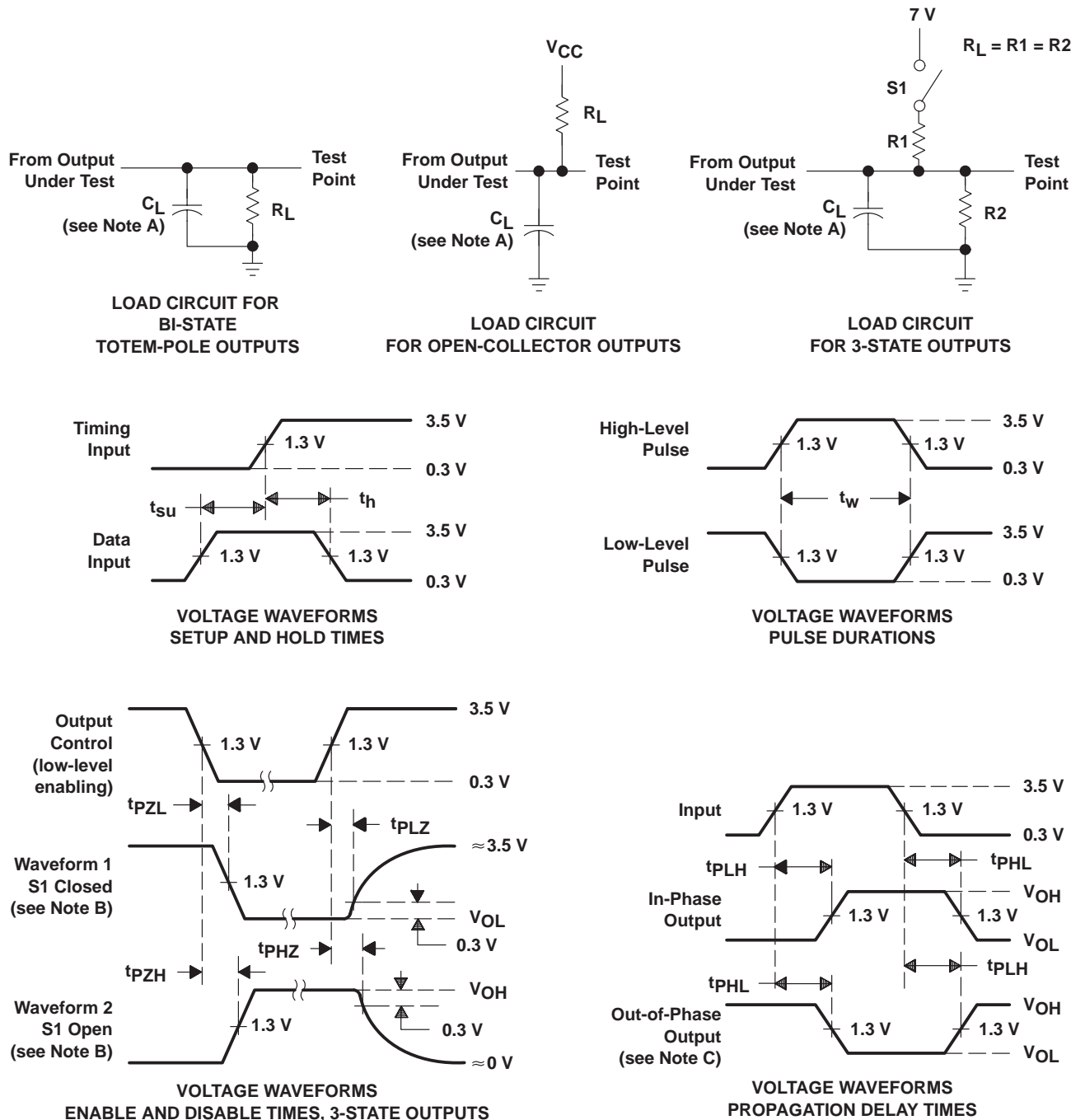| PARAMETER	TEST CONDITIONS		MIN	TYP‡	MAX	UNIT
V_{IK}	$V_{CC} = 4.5$ V,	$I_I = -18$ mA			−1.2	V
V_{OH}	$V_{CC} = 4.5$ V to 5.5 V,	$I_{OH} = -2$ mA	$V_{CC} - 2$			V
	$V_{CC} = 4.5$ V	$I_{OH} = -3$ mA	2.4	3.2		
		$I_{OH} = -48$ mA	2			
V_{OL}	$V_{CC} = 4.5$ V,	$I_{OL} = 48$ mA		0.35	0.5	V
I_I	$V_{CC} = 5.5$ V,	$V_I = 7$ V			0.1	mA
I_{IH}	$V_{CC} = 5.5$ V,	$V_I = 2.7$ V			20	µA
I_{IL}	$V_{CC} = 5.5$ V,	$V_I = 0.4$ V			−0.5	mA
I_O§	$V_{CC} = 5.5$ V,	$V_O = 2.25$ V	−50		−200	mA
I_{CCH}	$V_{CC} = 5.5$ V,	$V_I = 4.5$ V		5.6	9.5	mA
I_{CCL}	$V_{CC} = 5.5$ V,	$V_I = 0$		13.5	22	mA

‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25$°C.
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5$ V to 5.5 V, $C_L = 50$ pF, $R_L = 500$ Ω, $T_A = $ MIN to MAX¶		UNIT
			MIN	MAX	
t_{PLH}	A or B	Y	1	6	ns
t_{PHL}	A or B	Y	1	6	ns

¶ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES

LOAD CIRCUIT FOR
BI-STATE
TOTEM-POLE OUTPUTS

LOAD CIRCUIT
FOR OPEN-COLLECTOR OUTPUTS

LOAD CIRCUIT
FOR 3-STATE OUTPUTS

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATIONS

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
      Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
   D. All input pulses have the following characteristics: PRR ≤ 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
   E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

![Texas Instruments logo] **TEXAS INSTRUMENTS**

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AS1008AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1008A	Samples
SN74AS1008ADE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS1008A	Samples
SN74AS1008AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS1008AN	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

TUBE

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AS1008AD	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS1008ADE4	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS1008AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS1008AN	N	PDIP	14	25	506	13.97	11230	4.32

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
△C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) △D

1   7

Pin 1
Index Area

0.050 (1,27)   0.020 (0,51)
                    0.012 (0,31)

⊕ | 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
         △D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
         E. Reference JEDEC MS−012 variation AB.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

←12x1,27

←14x0,55

←12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

←0,60

1,55

Example
Solder Mask Opening
(See Note E)

←0.07
All Around

4211283−3/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

TEXAS
INSTRUMENTS
www.ti.com

N (R−PDIP−T**)

16 PINS SHOWN

PLASTIC DUAL−IN−LINE PACKAGE

PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) ⬠D

0.045 (1,14) / 0.030 (0,76) ⬠D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

14/18 Pin Only
20 Pin vendor option ⬠D

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
⬠C Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
⬠D The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.